

• General Description

The ZMS035N08HB combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

• Features

- Advance device constructure
- Low $R_{DS(ON)}$ to minimize conduction loss
- Low Gate Charge for fast switching
- Low Thermal resistance

• Application

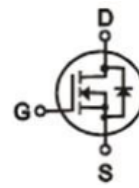
- Synchronous Rectification for AC-DC/DC-DC converter
- Oring switches
- Power Tools

• Ordering Information:

Part NO.	ZMS035N08HB
Marking	ZMS035N08H
Packing Information	Bulk Tube
Basic ordering unit (pcs)	800

• Absolute Maximum Ratings ($T_c = 25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	80	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_{D@TC=25^\circ\text{C}}$	140	A
	$I_{D@TC=75^\circ\text{C}}$	106.4	A
	$I_{D@TC=100^\circ\text{C}}$	88.2	A
Pulsed Drain Current ①	I_{DM}	320	A
Total Power Dissipation($TC=25^\circ\text{C}$)	$P_D@TC=25^\circ\text{C}$	150	W
Operating Junction Temperature	T_J	-55 to 150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 to 150	$^\circ\text{C}$
Single Pulse Avalanche Energy@ $L=0.1\text{mH}$	E_{AS}	125	mJ
Avalanche Current@ $L=0.1\text{mH}$	I_{AS}	50	A

• Product Summary


$V_{DS} = 80\text{V}$

$R_{DS(ON)} = 3.5\text{m}\Omega$

$I_D = 140\text{A}$



TO-263

•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	0.75	° C/W
Thermal resistance, junction - ambient	R_{thJA}	-	-	70	° C/W
Soldering temperature, wavesoldering for 10s	T_{sold}	-	-	265	° C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	80			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	2		4	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS} = 80V, V_{GS} = 0V$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			± 100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 30A$		3.5	4.5	m Ω
Forward Transconductance	g_{FS}	$V_{DS} = 10V, I_D = 40A$		28		s
Source-drain voltage	V_{SD}	$I_S = 30A$			1.28	V

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C_{iss}	f = 1MHz	-	3100	-	pF
Output capacitance	C_{oss}		-	890	-	
Reverse transfer capacitance	C_{rss}		-	130	-	

•Gate Charge characteristics($T_a = 25^\circ C$)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	Q_g	$V_{DD} = 40V$	-	42	-	nC
Gate - Source charge	Q_{gs}	$I_D = 30A$	-	12	-	
Gate - Drain charge	Q_{gd}	$V_{GS} = 10V$	-	9	-	

Note: ① Pulse Test : Pulse width $\leq 10\mu s$, Duty cycle $\leq 1\%$;

Fig.1 Gate-Charge Characteristics

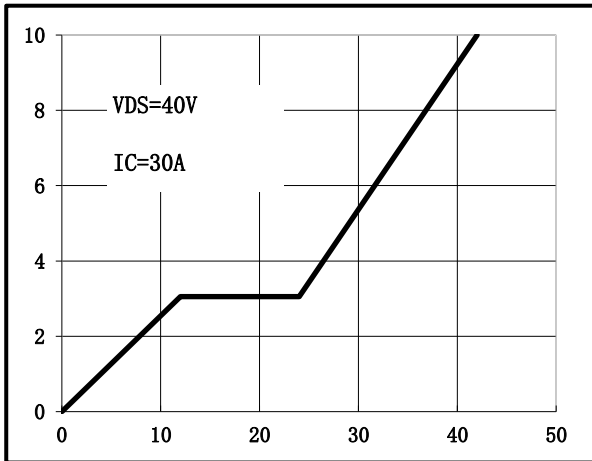


Fig.2 Capacitance Characteristics

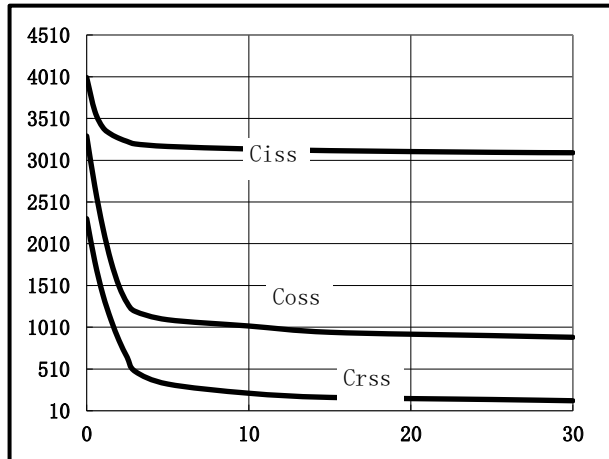


Fig.3 Power Dissipation

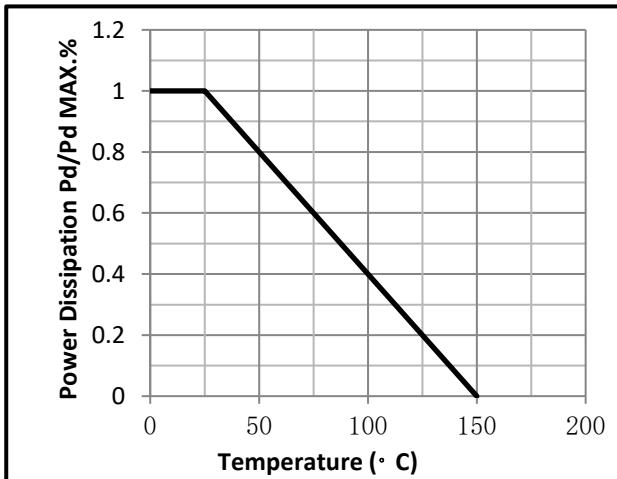


Fig.4 Typical output Characteristics

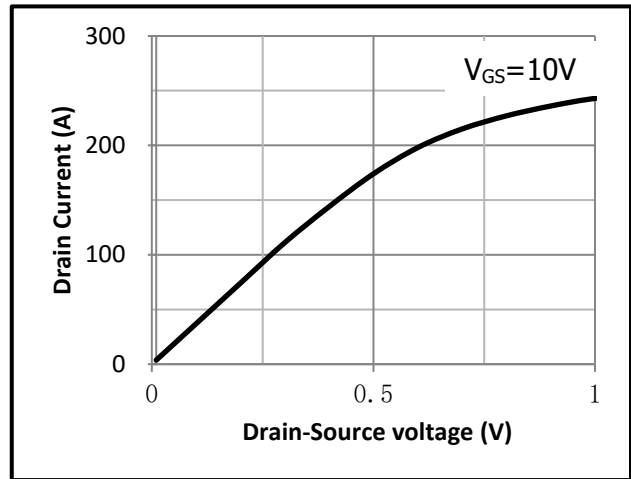


Fig.5 Threshold Voltage V.S Junction Temperature

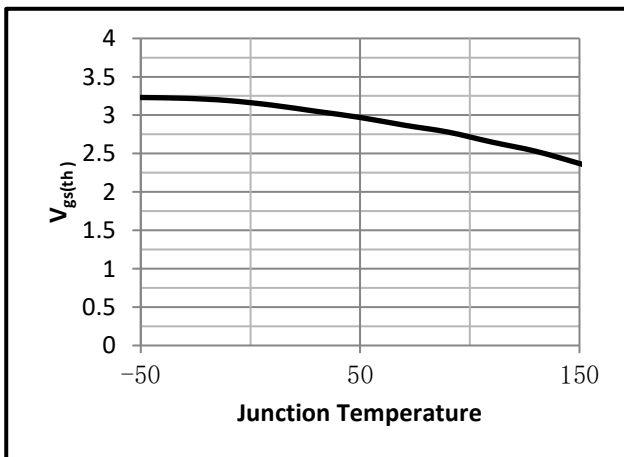


Fig.6 Resistance V.S Drain Current

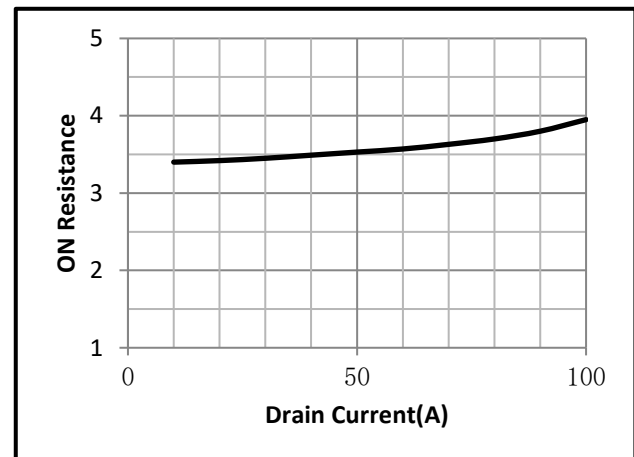


Fig.7 On-Resistance VS Gate Source Voltage

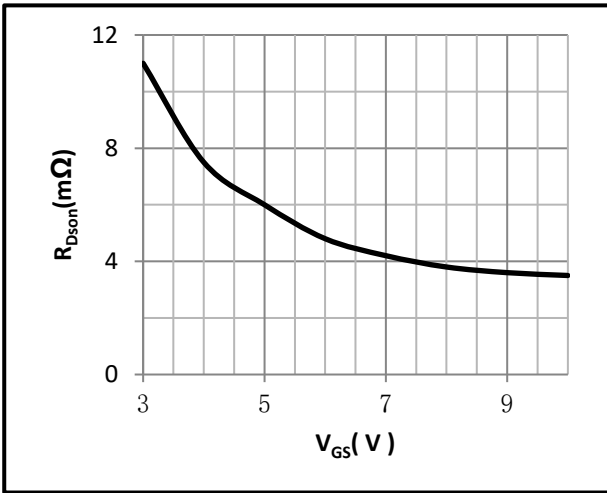


Fig.8 On-Resistance V.S Junction Temperature

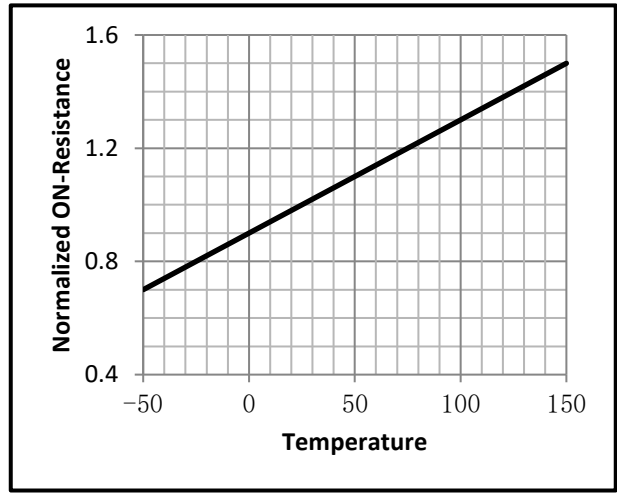


Fig.9 Switching Time Measurement Circuit

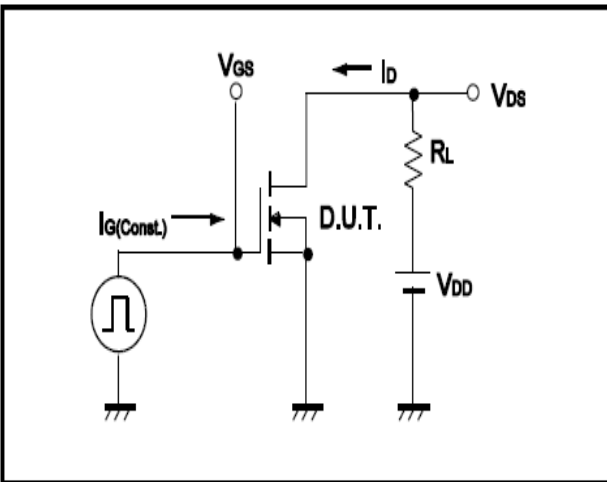


Fig.10 Gate Charge Waveform

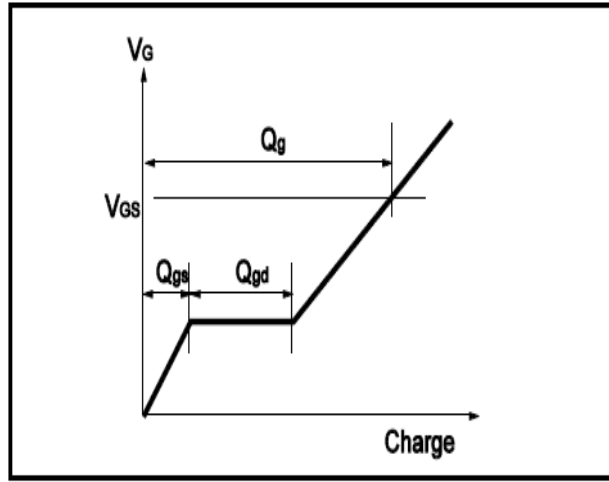


Fig.11 Switching Time Measurement Circuit

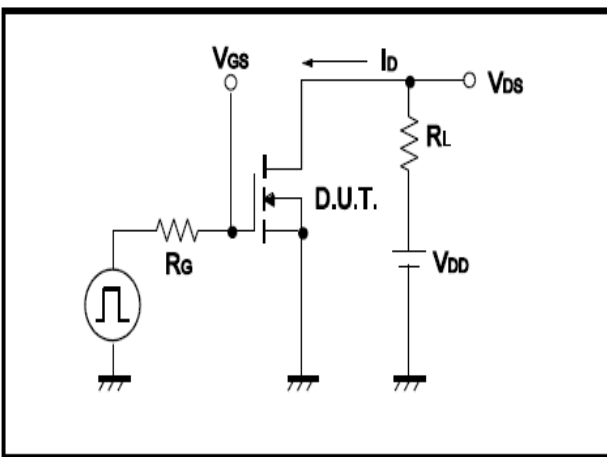
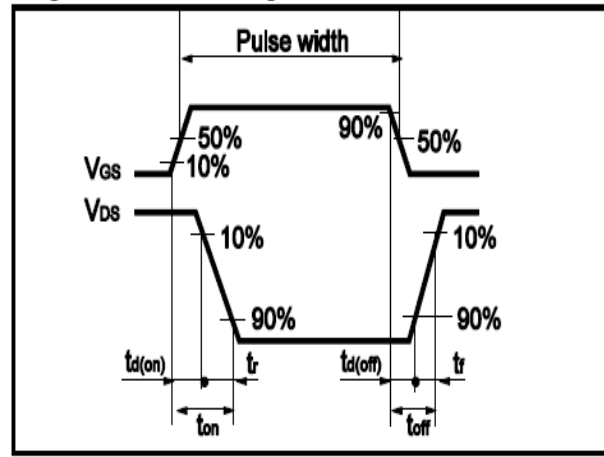


Fig.12 Gate Charge Waveform



• Dimensions (TO-263)

Unit: mm

SYMBOL	MIN	TYP	MAX	SYMBOL	MIN	TYP	MAX
A	4.42		4.72	E	8.99		9.29
B	1.22		1.32	e1	2.44		2.64
b	0.76		0.86	e2	4.98		5.18
b1	1.22		1.32	L1	15.19		15.79
b2	0.33		0.43	L2	2.29		2.79
C	1.22		1.32	L3	1.3		1.75
D	9.95		10.25				

